Supplementary Information

The rational design of hierarchical $CoS_2/CuCo_2S_4$ for threedimensional all-solid-state hybrid supercapacitors with high energy density, rate efficiency, and operational stability

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Scheme S1 Plausible mechanism for the formation of CoS₂/CuCo₂S₄ rod-like microstructure.

Table S1. List of major peaks (binding energy) as shown in the survey XPS profile of $CoS_2/CuCo_2S_4$ and their corresponding attributions

| Binding energy (eV) | Attribution |
|---------------------|----------------------|
| 952.30 | Cu 2p _{1/2} |
| 932.40 | Cu 2p _{3/2} |
| 838.42 | shake-up satellite |
| 796.78 | shake-up satellite |
| 778.3 | Co 2p |
| 712.27 | shake-up satellite |
| 530.9 | O 1s |
| 284.15 | C 1s |
| 224.46 | S 2s |
| 160.76 | S 2p |
| 121.89 | Cu 3s |
| 102.5 | Co 3s |
| 74.99 | Cu 3p |
| 58.18 | Co 3p |



Fig. S1 FESEM image of $CoS_2/CuCo_2S_4$, which has been used for EDX elemental mapping.



Fig. S2 Linear-fitted *log v* vs. *log i* plot of $CoS_2/CuCo_2S_4$

Table S2. Comparison of the specific capacitance and charge transfer resistance values of $CoS_2/CuCo_2S_4$ with reported $CuCo_2S_4$ -based materials.

| Sl. No. | Sample Name | C _s @Current Density (3-Electrode Setup) | C _s @Scan Rate (3-Electrode Setup) | R _{ct} (Ω) from EIS (3-Electrode Setup) | Reference |
|------------|---|---|--|--|-----------|
| 1 | CuCo ₂ S ₄ dandelion-like | 424 F g ⁻¹ @1 A g ⁻¹ | - | - | [s1] |
| 2 | CuCo ₂ S ₄ @CNT | 1690 F g ⁻¹ @1 A g ⁻¹ | - | - | [s2] |
| 3 | CuCo ₂ S ₄ -rGO | 525 F $g^{-1}@1 A g^{-1}$; 425 F $g^{-1}@5 A g^{-1}$; 370 F $g^{-1}@10 A g^{-1}$; 326 F $g^{-1}@15 A g^{-1}$; 303 F $g^{-1}@20 A g^{-1}$ | 665 F g ⁻¹ @ 7.5 mV s ⁻¹ | - | [s3] |
| 4 | CNTs@NC@CuCo ₂ S ₄ | 1604 F g^{-1} @1 A g^{-1} ; 1044 F g^{-1} @2 A g^{-1} ; 1000 F g^{-1} @5 A g^{-1} ; 955 F g^{-1} @10 A g^{-1} ; 896 F g^{-1} @20 A g^{-1} | - | 135.6 | [s4] |
| 5 | CuCo ₂ S ₄ -HNN (hollow nano-needle arrays) | 2163 F g ⁻¹ @6 A g ⁻¹ | - | - | [s5] |
| 6 | CuCo ₂ S ₄ /CNT/Graphene | 504 F g ⁻¹ @10 A g ⁻¹ | - | - | [s6] |

| 7 | $CuCo_2S_4$ nanowire | 875 F g ⁻¹ @1 A g ⁻¹ | - | 1.96 | [s7] |
|----|--|--|--|------|-------|
| 8 | $CuCo_2S_4$ nanorod array | 1536 F g^{-1} @1 A g^{-1} ; 1295 F g^{-1} @5 A g^{-1} ; 1157 F g^{-1} @10 A g^{-1} ; 1026 F g^{-1} @20 A g^{-1} | - | - | [s8] |
| 9 | CuCo ₂ S ₄ /GA (graphene aerogel) | $\begin{array}{cccc} {}^{\prime} GA & 668 \ F \ g^{-1} @ 1 \ A \ g^{-1}; & - & - \\ erogel) & 620 \ F \ g^{-1} @ 2 \ A \ g^{-1}; \\ & 588 \ F \ g^{-1} @ 5 \ A \ g^{-1}; \\ & 535 \ F \ g^{-1} @ 10 \ A \ g^{-1}; \\ & 480 \ F \ g^{-1} @ 20 \ A \ g^{-1} \end{array}$ | | - | [s9] |
| 10 | CuCo ₂ S ₄ micro-sphere | 516 F g^{-1} @10 A g^{-1} | $\begin{array}{l} 665 \ F \ g^{-1} @ 10 \ mV \ s^{-1}; \\ 482 \ F \ g^{-1} @ 50 \ mV \ s^{-1} \end{array}$ | 0.26 | [s10] |
| 11 | CuCo ₂ S ₄ nanoparticle | 772 F g^{-1} @2 A g^{-1} | - | - | [s11] |
| 12 | CuCo ₂ S ₄ ball-in-ball | 442 F g^{-1} @0.5 A g^{-1} | - | - | [s12] |
| 13 | CuCo ₂ S ₄ agglomerate nanoparticle | 580 F $g^{-1}@1$ A g^{-1} ; 529 F $g^{-1}@2$ A g^{-1} ; 482 F $g^{-1}@3$ A g^{-1} ; 437 F $g^{-1}@4$ A g^{-1} ; 406 F $g^{-1}@5$ A g^{-1} ; 354 F $g^{-1}@7$ A g^{-1} | _ | 5.65 | [s13] |
| 14 | CuCo ₂ S ₄ microsphere 1566 F g^{-1} @2 A g^{-1} | | - | 0.27 | [s14] |
| 15 | CuCo ₂ S ₄ /NG (N-doped graphene) | 1005 F g^{-1} @1 A g^{-1} ; 978 F g^{-1} @3 A g^{-1} ; 949 F g^{-1} @5 A g^{-1} ; 901 F g^{-1} @10 A g^{-1} ; 831 F g^{-1} @20 A g^{-1} | _ | _ | [s15] |
| 16 | C@CuCo ₂ S ₄ | 854 F g^{-1} @1 A g^{-1} ; 774 F g^{-1} @3 A g^{-1} ; 681 F g^{-1} @5 A g^{-1} ; 597 F g^{-1} @7 A g^{-1} ; 485 F g^{-1} @10 A g^{-1} | _ | _ | [s16] |
| 17 | $CuCo_2S_4$ nanoparticles | 449 F g^{-1} @1 A g^{-1} ; 443 F g^{-1} @1.5 A g^{-1} ; 433 F g^{-1} @3 A g^{-1} ; 401 F g^{-1} @5 A g^{-1} | - | 0.56 | [s17] |
| 18 | GQD (graphene quantum dots)/CuCo ₂ S ₄ | 1725 F g ⁻¹ @0.1 A g ⁻¹ | - | | [s18] |

| 19 | N-doped C-coated CuCo ₂ S ₄ | 1228 F g^{-1} @1 A g^{-1} ; 1070 F g^{-1} @2 A g^{-1} ; 1003 F g^{-1} @3 A g^{-1} ; 933 F g^{-1} @5 A g^{-1} ; 864 F g^{-1} @10 A g^{-1} ; 784 F g^{-1} @20 A g^{-1} | 2002 F g ⁻¹ @5 mV s ⁻¹ ; 1831 F g ⁻¹ @10 mV s ⁻¹ ; 1535 F g ⁻¹ @ 20 mV s ⁻¹ ; 1168 F g ⁻¹ @50 mV s ⁻¹ ; 921 F g ⁻¹ @ 100 mV s ⁻¹ | 0.39 | [s19] |
|----|--|---|--|------|-----------|
| 20 | CoS ₂ /CuCo ₂ S ₄ | 2438 F g^{-1} @2 A g^{-1} ; 1995 F g^{-1} @3 A g^{-1} ; 1730 F g^{-1} @4 A g^{-1} ; 1590 F g^{-1} @5 A g^{-1} ; 1492 F g^{-1} @6 A g^{-1} | $\begin{array}{l} 4653 \ F \ g^{-1} @ 10 \ mV \ s^{-1}; \\ 3618 \ F \ g^{-1} @ 20 \ mV \ s^{-1}; \\ 3007 \ F \ g^{-1} @ \ 30 \ mV \ s^{-1}; \\ 2552 \ F \ g^{-1} @ 40 \ mV \ s^{-1}; \\ 2169 \ F \ g^{-1} @ \ 50 \ mV \ s^{-1} \end{array}$ | 0.23 | This work |

Table S3. Comparison of the energy density, power density and multiple-cycle capacitanceretention of $CoS_2/CuCo_2S_4$ ||N-rGO ASSHSC device with reported $CuCo_2S_4$ -based hybridsupercapacitor devices.

| Sl. No. | Hybrid Supercapacitor Device | Energy Density $(E_D; W h Kg^{-1})$ | Power Density (<i>P_D</i> ; W Kg ⁻¹) | Capacitance Retention (%/No. of cycle) | Reference |
|------------|---|-------------------------------------|--|--|-----------|
| 1 | CuCo ₂ S ₄ /CC AC | 17.12 | 194.4 | 78.4 / 3,000 | [s20] |
| 2 | CuCo ₂ S ₄ GA | 22 | 1080 | 70.4 / 5,000 | [s9] |
| 3 | CuCo ₂ S ₄ /CNT AC | 23.2 | 402.7 | 85.7 / 10,000 | [s21] |
| 4 | CuCo ₂ S ₄ /N,S-RGO N,S-RGO | 10.8 | 400 | 88.9 / 5,000 | [s22] |
| 5 | CuCo ₂ S ₄ @NiCo ₂ S ₄ AC | 23.4 | 400 | 71 / 3,000 | [s23] |
| 6 | CuCo ₂ S ₄ AC | 15.0 | 422.5 | 94.7 / 5,000 | [s17] |
| 7 | CuCo ₂ S ₄ AC-ASC | 16 | 240 | 99.5 / 6,000 | [s13] |
| 8 | CuCo ₂ S ₄ AC | 22 | 405 | 62 / 20,000 | [s1] |
| 9 | CoS ₂ /CuCo ₂ S ₄ N-rGO | 32.4 | 4000 | 92.8 /10,000 | This work |

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